1 substrate, the first generally circular solder pad having a center, and having a first

2 predetermined diameter D;

3   b.   a second generally circular solder pad formed upon the upper surface of the first

4 substrate, the second generally circular solder pad having a center, and having said first

5 predetermined diameter D, the center of said second generally circular solder pad being spaced

6 from the center of said first generally circular solder pad by a predetermined spacing distance

7 BL;

8   c.   a solder bar pad of a first predetermined bar width BW formed upon the upper

9 surface of the first substrate connecting said first circular solder pad to said second circular

10 solder pad, the first predetermined bar width BW being less than the first predetermined

11 diameter D;

12   d.   a mass of low melting temperature reflowable solder having a solder bar volume

13 VB formed over the first and second generally circular solder pads and over said solder bar pad

14 to form said reflowable solder bar, the solder bar volume VB reaching a height H1 above the

15 centers of said first and second generally circular solder pads, and reaching a height H2 above

16 a midpoint of said solder bar pad, the mass of low melting temperature reflowable solder

17 having a lowermost base region adjacent said solder bar pad, the width of the lower most base

18 region of the solder mass along the solder bar pad being substantially equal to solder bar pad

19 width BW;

20   e.   wherein the values for predetermined diameter D, spacing distance BL,

21 predetermined bar width BW, and solder bar volume VB are selected in such manner that H1

22 and H2 are approximately equal.

23

24   Please replace claims 17-22 with the following amended claims:

25   17. (Amended) The reflowable solder bar recited by claim 16 wherein conventional

26 generally circular (as viewed from above) solder bumps are also formed upon the upper

27 surface of the first substrate, the conventional generally circular solder bumps having a height

28 H3, and wherein height H1 and height H2 of said solder bar are approximately equal to height

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